

0,635mm MICRO EDGE-CARD MEC6-DV SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC6-DV

- Insulator Material:** Black LCP
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50µ" (1,27µm) Ni
- Operating Temp Range:** -55°C to +125°C
- Insertion Depth:** (4,22mm) .166" to (5,66mm) .223"
- Current Rating:** Testing Now!
- Voltage Rating:** Testing Now!

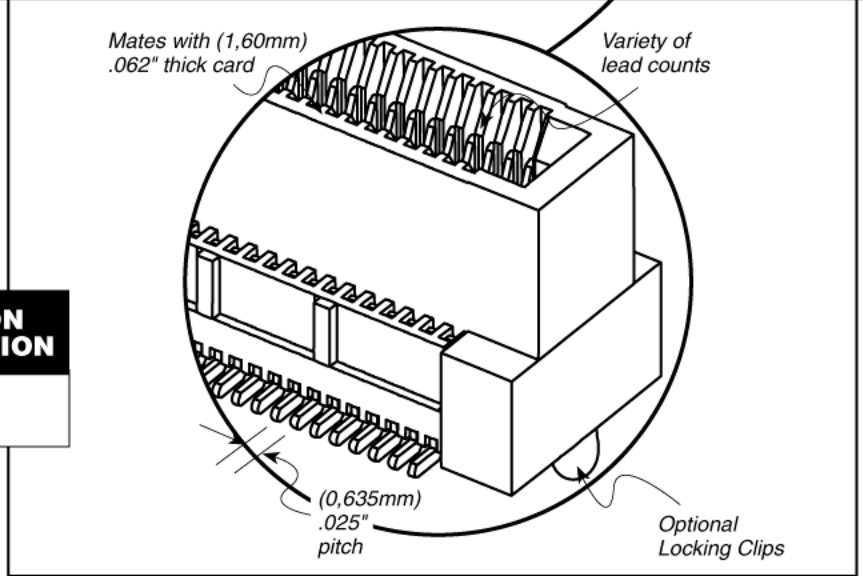
Processing:

- Max Processing Temp:** 230°C for 60 seconds, or 260°C for 20 seconds 3x
- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0,10mm) .004" max (10-50) (0,15mm) .006" max (60-70)

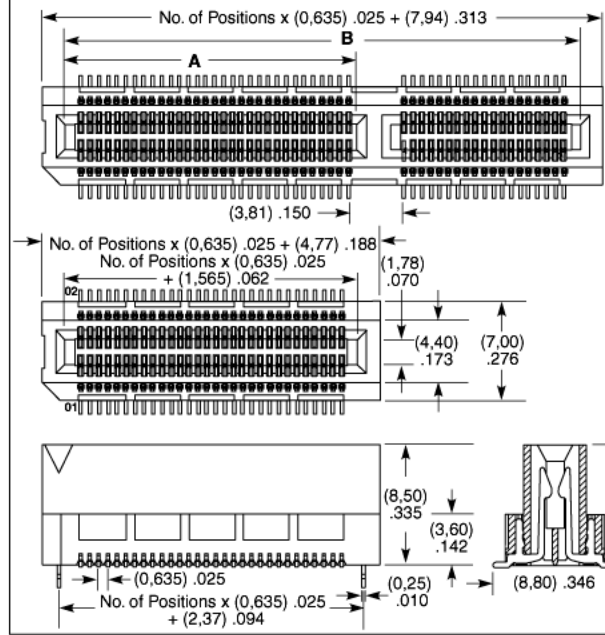
Mates with:
(1,60mm) .062" thick cards

APPLICATION SPECIFIC OPTION

- Locking Clip
Call Samtec.



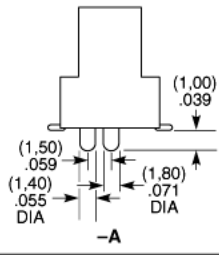
10, 20, 30, 40, 50, 60, 70



- S** = 30µ" (0,76µm) Gold on contact, Matte Tin on tail
- L** = 10µ" (0,25µm) Gold on contact, Matte Tin on tail

- K** = (5,50) .217" DIA Polyimide Pick & Place Pad
- TR** = Tape & Reel

POSITIONS PER ROW	A	B
50	(22,96) .904	(36,49) 1.437
60	(24,87) .979	(42,84) 1.687
70	(28,68) 1.129	(49,19) 1.937



Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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